

115-3302 Circuit Bond Epoxy

Clear, low-viscosity, superior-strength epoxy is precisely measured into two-compartment plastic packages, so it's easy to use and requires no measuring. Thousands of high-reliability electronics manufacturers worldwide have qualified and used this high-strength epoxy.



Ship FedEx and UPS Only.

Specifications

Packaging	2 gram pre-measured packages
Mix ratio	4 parts resin to 1 part hardener
Mix Ratio by Weight (R/H)	100/25
Color	Clear, transparent
Pot life	30 minutes
Cure cycle	24 hours at room temp (25 °C) or 4 hours @ 65°C
Thixotropic Index	1
Specific Gravity	1.20
Percent Solids	100%
Viscosity (after mixing)	2000 cps
Operating temperature range	-55°C to 135°C
Hardness	88 Shore D
Lap Shear, Alum to Alum	1100 psi
Glass Transition Temperature, Ultimate	92°C
Coefficient of Expansion, cm/cm/°C	6 E-05
Dielectric strength	400 volts/mil
Dielectric Constant, 1KHz@25°C	4
Shelf Life	6 months minimum



How To Use Istructions

1. Circuit Bond has a working pot life of 30 minutes. It should not be mixed until ready to use.
2. To use Circuit Bond, remove the plastic clip separating the resin and hardener. Squeeze back and forth from one half of the package to the other to mix the contents.
3. Cut a corner off the package and squeeze all the contents into a plastic cup. Stir the contents to ensure it is thoroughly mixed.
4. NOTE: Circuit Bond may contain bubbles from the mixing process. If needed, use a vacuum system to remove bubbles.
5. If desired, a color agent can be mixed with Circuit Bond to match surface colors.
6. Apply using a foam swab, micro-probe, or mixing stick as required.
7. Cure Circuit Bond for 24 hours at room temperature or 4 hours at 65°C (150°F).

Classifications

Harmonize Code	3506.91.0000
Export Administration Regulations (EAR)	EAR99
Export Control Classification Number (ECCN)	Not Applicable